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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1057
Number of Logic Elements/Cells	10570
Total RAM Bits	920448
Number of I/O	335
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA, FCBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s10f484c7n



Chapter Revision Dates	vii
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About This Handbook	ix
----------------------------------	-----------

How to Find Information	ix
How to Contact Altera	ix
Typographic Conventions	x

Section I. Stratix Device Family Data Sheet

Revision History	Part I-1
------------------------	----------

Chapter 1. Introduction

Introduction	1-1
Features	1-2

Chapter 2. Stratix Architecture

Functional Description	2-1
Logic Array Blocks	2-3
LAB Interconnects	2-4
LAB Control Signals	2-5
Logic Elements	2-6
LUT Chain & Register Chain	2-8
addsub Signal	2-8
LE Operating Modes	2-8
Clear & Preset Logic Control	2-13
MultiTrack Interconnect	2-14
TriMatrix Memory	2-21
Memory Modes	2-22
Clear Signals	2-24
Parity Bit Support	2-24
Shift Register Support	2-25
Memory Block Size	2-26
Independent Clock Mode	2-44
Input/Output Clock Mode	2-46
Read/Write Clock Mode	2-49
Single-Port Mode	2-51
Multiplier Block	2-57
Adder/Output Blocks	2-61
Modes of Operation	2-64

Maximum Input & Output Clock Rates	4-76
High-Speed I/O Specification	4-87
PLL Specifications	4-94
DLL Specifications	4-102

Chapter 5. Reference & Ordering Information

Software	5-1
Device Pin-Outs	5-1
Ordering Information	5-1

Index



Chapter Revision Dates

The chapters in this book, *Stratix Device Handbook, Volume 1*, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

- Chapter 1. Introduction
Revised: *July 2005*
Part number: *S51001-3.2*
- Chapter 2. Stratix Architecture
Revised: *July 2005*
Part number: *S51002-3.2*
- Chapter 3. Configuration & Testing
Revised: *July 2005*
Part number: *S51003-1.3*
- Chapter 4. DC & Switching Characteristics
Revised: *January 2006*
Part number: *S51004-3.4*
- Chapter 5. Reference & Ordering Information
Revised: *September 2004*
Part number: *S51005-2.1*

Introduction

The Stratix® family of FPGAs is based on a 1.5-V, 0.13-μm, all-layer copper SRAM process, with densities of up to 79,040 logic elements (LEs) and up to 7.5 Mbits of RAM. Stratix devices offer up to 22 digital signal processing (DSP) blocks with up to 176 (9-bit × 9-bit) embedded multipliers, optimized for DSP applications that enable efficient implementation of high-performance filters and multipliers. Stratix devices support various I/O standards and also offer a complete clock management solution with its hierarchical clock structure with up to 420-MHz performance and up to 12 phase-locked loops (PLLs).

The following shows the main sections in the Stratix Device Family Data Sheet:

Section	Page
Features	1-2
Functional Description	2-1
Logic Array Blocks.	2-3
Logic Elements	2-6
MultiTrack Interconnect	2-14
TriMatrix Memory	2-21
Digital Signal Processing Block	2-52
PLLs & Clock Networks	2-73
I/O Structure	2-104
High-Speed Differential I/O Support.	2-130
Power Sequencing & Hot Socketing	2-140
IEEE Std. 1149.1 (JTAG) Boundary-Scan Support.	3-1
SignalTap II Embedded Logic Analyzer	3-5
Configuration	3-5
Temperature Sensing Diode.	3-13
Operating Conditions	4-1
Power Consumption	4-17
Timing Model.	4-19
Software.	5-1
Device Pin-Outs	5-1
Ordering Information	5-1

The Quartus II software, in conjunction with parameterized functions such as library of parameterized modules (LPM) functions, automatically chooses the appropriate mode for common functions such as counters, adders, subtractors, and arithmetic functions. If required, you can also create special-purpose functions that specify which LE operating mode to use for optimal performance.

The normal mode is suitable for general logic applications and combinatorial functions. In normal mode, four data inputs from the LAB local interconnect are inputs to a four-input LUT (see [Figure 2-6](#)). The Quartus II Compiler automatically selects the carry-in or the `data3` signal as one of the inputs to the LUT. Each LE can use LUT chain connections to drive its combinatorial output directly to the next LE in the LAB. Asynchronous load data for the register comes from the `data3` input of the LE. LEs in normal mode support packed registers.

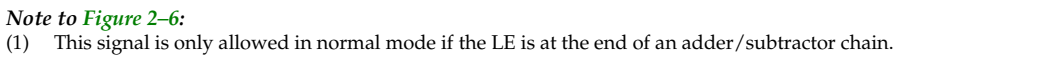


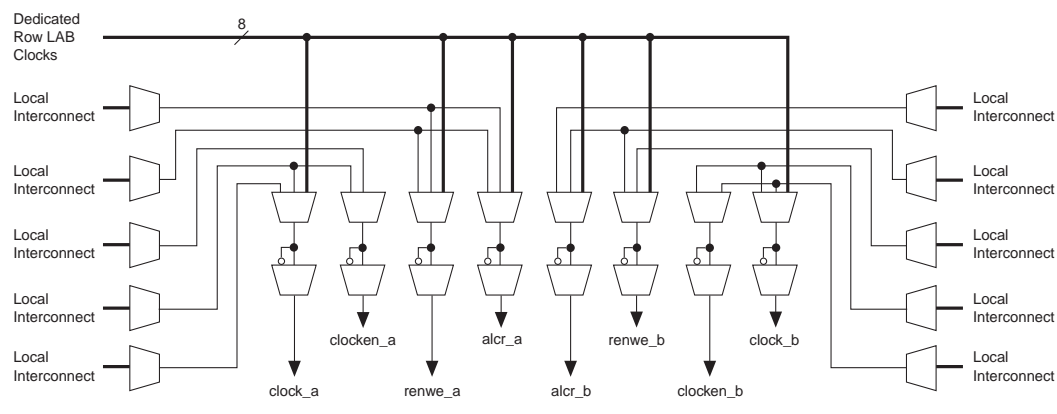
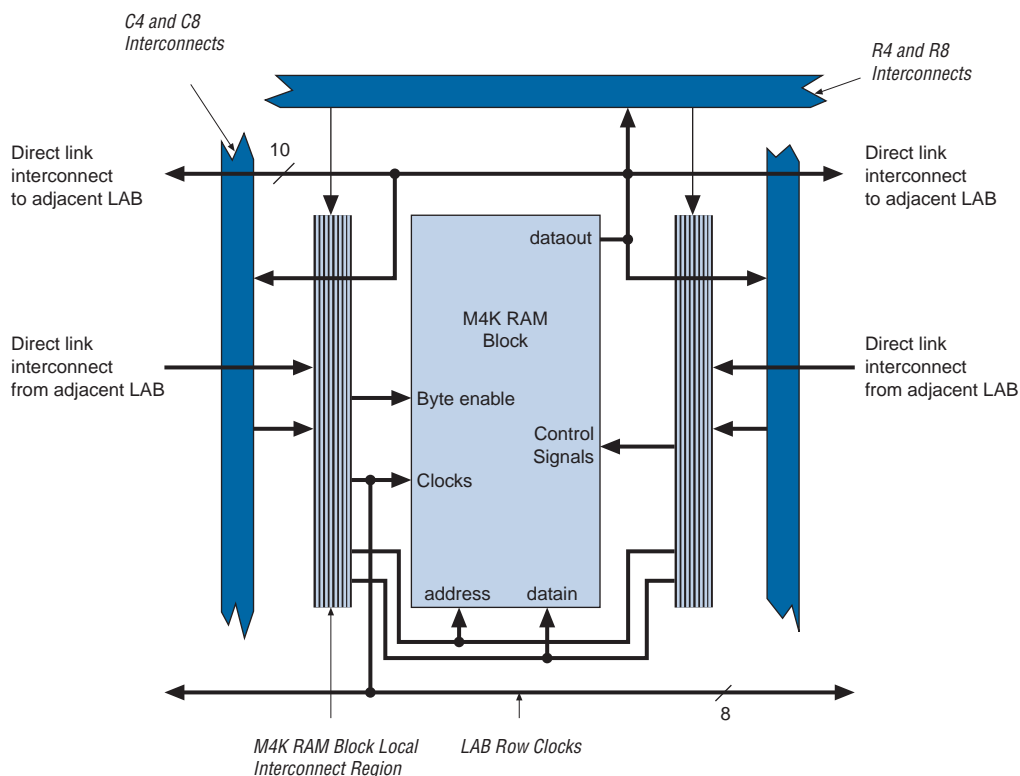
Figure 2–17. M4K RAM Block Control Signals**Figure 2–18. M4K RAM Block LAB Row Interface**

Figure 2–22. M-RAM Row Unit Interface to Interconnect

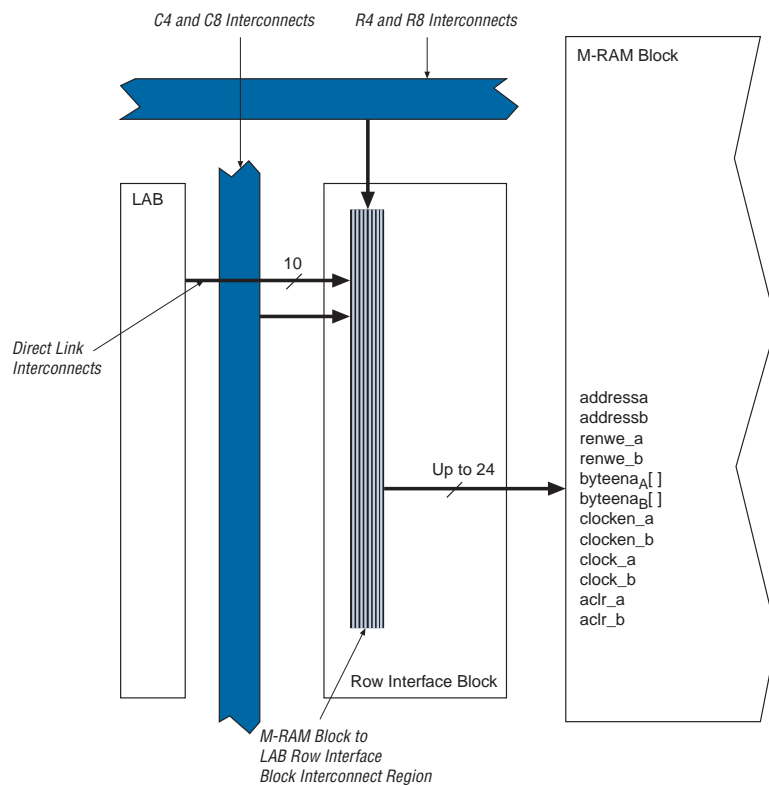
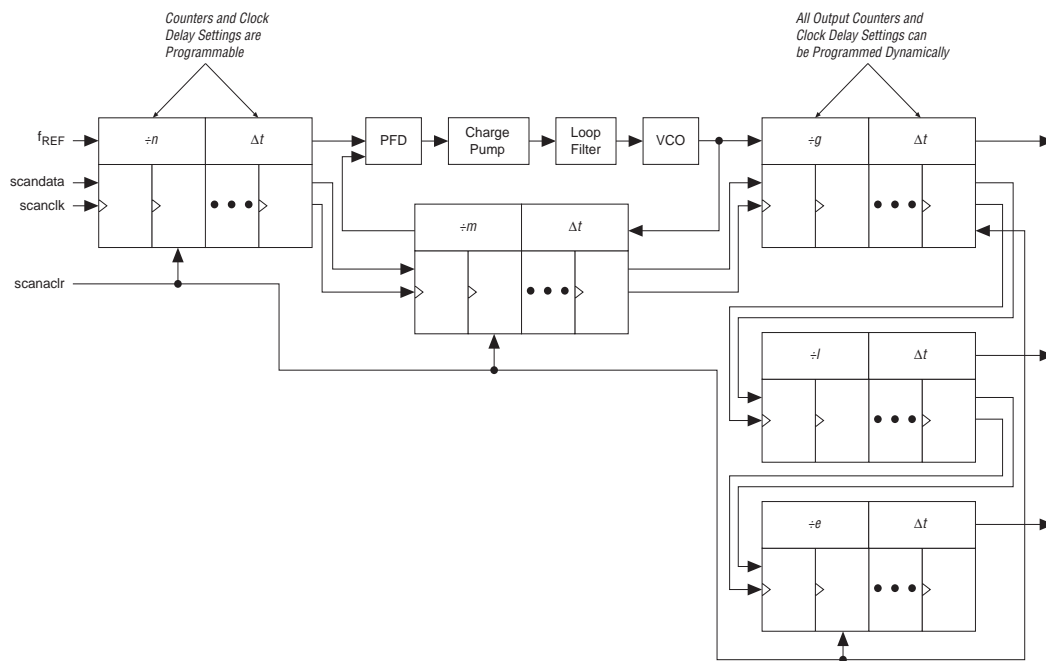


Figure 2–54. Dynamically Programmable Counters & Delays in Stratix Device Enhanced PLLs

PLL reconfiguration data is shifted into serial registers from the logic array or external devices. The PLL input shift data uses a reference input shift clock. Once the last bit of the serial chain is clocked in, the register chain is synchronously loaded into the PLL configuration bits. The shift circuitry also provides an asynchronous clear for the serial registers.



For more information on PLL reconfiguration, see *AN 282: Implementing PLL Reconfiguration in Stratix & Stratix GX Devices*.

Programmable Bandwidth

You have advanced control of the PLL bandwidth using the programmable control of the PLL loop characteristics, including loop filter and charge pump. The PLL's bandwidth is a measure of its ability to track the input clock and jitter. A high-bandwidth PLL can quickly lock onto a reference clock and react to any changes in the clock. It also will allow a wide band of input jitter spectrum to pass to the output. A low-bandwidth PLL will take longer to lock, but it will attenuate all high-frequency jitter components. The Quartus II software can adjust PLL characteristics to achieve the desired bandwidth. The programmable

External Clock Inputs

Each fast PLL supports single-ended or differential inputs for source synchronous transmitters or for general-purpose use. Source-synchronous receivers support differential clock inputs. The fast PLL inputs are fed by CLK [0 . . 3], CLK [8 . . 11], and FPLL [7 . . 10] CLK pins, as shown in [Figure 2–50 on page 2–85](#).

[Table 2–22](#) shows the I/O standards supported by fast PLL input pins.

Table 2–22. Fast PLL Port I/O Standards (Part 1 of 2)		
I/O Standard	Input	
	INCLK	PLEENABLE
LVTTTL	✓	✓
LVC MOS	✓	✓
2.5 V	✓	
1.8 V	✓	
1.5 V	✓	
3.3-V PCI		
3.3-V PCI-X 1.0		
LVPECL	✓	
3.3-V PCML	✓	
LVDS	✓	
HyperTransport technology	✓	
Differential HSTL	✓	
Differential SSTL		
3.3-V GTL		
3.3-V GTL+	✓	
1.5-V HSTL Class I	✓	
1.5-V HSTL Class II		
1.8-V HSTL Class I	✓	
1.8-V HSTL Class II		
SSTL-18 Class I	✓	
SSTL-18 Class II		
SSTL-2 Class I	✓	

Table 2–41. EP1S80 Differential Channels (Part 2 of 2) Note (1)

Package	Transmitter/ Receiver	Total Channels	Maximum Speed (Mbps)	Center Fast PLLs				Corner Fast PLLs (2), (3)			
				PLL1	PLL2	PLL3	PLL4	PLL7	PLL8	PLL9	PLL10
1,508-pin FineLine BGA	Transmitter (4)	80 (72) (7)	840	10 (10)	10 (10)	10 (10)	10 (10)	20 (8)	20 (8)	20 (8)	20 (8)
			840 (5),(8)	20 (20)	20 (20)	20 (20)	20 (20)	20 (8)	20 (8)	20 (8)	20 (8)
	Receiver	80 (56) (7)	840	20	20	20	20	10 (14)	10 (14)	10 (14)	10 (14)
			840 (5),(8)	40	40	40	40	10 (14)	10 (14)	10 (14)	10 (14)

Notes to Tables 2–38 through 2–41:

- (1) The first row for each transmitter or receiver reports the number of channels driven directly by the PLL. The second row below it shows the maximum channels a PLL can drive if cross bank channels are used from the adjacent center PLL. For example, in the 780-pin FineLine BGA EP1S30 device, PLL 1 can drive a maximum of 18 transmitter channels at 840 Mbps or a maximum of 35 transmitter channels at 840 Mbps. The Quartus II software may also merge transmitter and receiver PLLs when a receiver is driving a transmitter. In this case, one fast PLL can drive both the maximum numbers of receiver and transmitter channels.
- (2) Some of the channels accessible by the center fast PLL and the channels accessible by the corner fast PLL overlap. Therefore, the total number of channels is not the addition of the number of channels accessible by PLLs 1, 2, 3, and 4 with the number of channels accessible by PLLs 7, 8, 9, and 10. For more information on which channels overlap, see the Stratix device pin-outs at www.altera.com.
- (3) The corner fast PLLs in this device support a data rate of 840 Mbps for channels labeled “high” speed in the device pin-outs at www.altera.com.
- (4) The numbers of channels listed include the transmitter clock output (tx_outclock) channel. An extra data channel can be used if a DDR clock is needed.
- (5) These channels span across two I/O banks per side of the device. When a center PLL clocks channels in the opposite bank on the same side of the device it is called cross-bank PLL support. Both center PLLs can clock cross-bank channels simultaneously if say PLL_1 is clocking all receiver channels and PLL_2 is clocking all transmitter channels. You cannot have two adjacent PLLs simultaneously clocking cross-bank receiver channels or two adjacent PLLs simultaneously clocking transmitter channels. Cross-bank allows for all receiver channels on one side of the device to be clocked on one clock while all transmitter channels on the device are clocked on the other center PLL. Crossbank PLLs are supported at full-speed, 840 Mbps. For wire-bond devices, the full-speed is 624 Mbps.
- (6) PLLs 7, 8, 9, and 10 are not available in this device.
- (7) The number in parentheses is the number of slow-speed channels, guaranteed to operate at up to 462 Mbps. These channels are independent of the high-speed differential channels. For the location of these channels, see the device pin-outs at www.altera.com.
- (8) See the Stratix device pin-outs at www.altera.com. Channels marked “high” speed are 840 MBps and “low” speed channels are 462 MBps.

The high-speed differential I/O circuitry supports the following high speed I/O interconnect standards and applications:

- UTOPIA IV
- SPI-4 Phase 2 (POS-PHY Level 4)
- SFI-4
- 10G Ethernet XSBI

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All Stratix® devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1a-1990 specification. JTAG boundary-scan testing can be performed either before or after, but not during configuration. Stratix devices can also use the JTAG port for configuration together with either the Quartus® II software or hardware using either Jam Files (.jam) or Jam Byte-Code Files (.jbc).

Stratix devices support IOE I/O standard setting reconfiguration through the JTAG BST chain. The JTAG chain can update the I/O standard for all input and output pins any time before or during user mode through the CONFIG_IO instruction. You can use this ability for JTAG testing before configuration when some of the Stratix pins drive or receive from other devices on the board using voltage-referenced standards. Since the Stratix device may not be configured before JTAG testing, the I/O pins may not be configured for appropriate electrical standards for chip-to-chip communication. Programming those I/O standards via JTAG allows you to fully test the I/O connection to other devices.

The enhanced PLL reconfiguration bits are part of the JTAG chain before configuration and after power-up. After device configuration, the PLL reconfiguration bits are not part of the JTAG chain.

The JTAG pins support 1.5-V/1.8-V or 2.5-V/3.3-V I/O standards. The TDO pin voltage is determined by the V_{CCIO} of the bank where it resides. The VCCSEL pin selects whether the JTAG inputs are 1.5-V, 1.8-V, 2.5-V, or 3.3-V compatible.

Stratix devices also use the JTAG port to monitor the logic operation of the device with the SignalTap® II embedded logic analyzer. Stratix devices support the JTAG instructions shown in [Table 3-1](#).

The Quartus II software has an Auto Usercode feature where you can choose to use the checksum value of a programming file as the JTAG user code. If selected, the checksum is automatically loaded to the USERCODE register. In the Settings dialog box in the Assignments menu, click **Device & Pin Options**, then **General**, and then turn on the **Auto Usercode** option.



Stratix, Stratix II, Cyclone®, and Cyclone II devices must be within the first 17 devices in a JTAG chain. All of these devices have the same JTAG controller. If any of the Stratix, Stratix II, Cyclone, and Cyclone II devices are in the 18th or after they will fail configuration. This does not affect SignalTap II.



For more information on JTAG, see the following documents:

- *AN 39: IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*
- *Jam Programming & Test Language Specification*

SignalTap II Embedded Logic Analyzer

Stratix devices feature the SignalTap II embedded logic analyzer, which monitors design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry. You can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages, such as FineLine BGA® packages, because it can be difficult to add a connection to a pin during the debugging process after a board is designed and manufactured.

Configuration

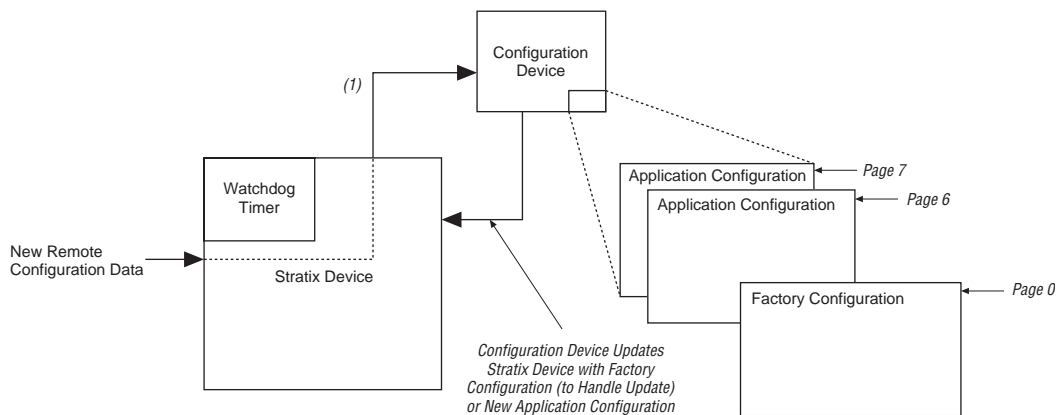
The logic, circuitry, and interconnects in the Stratix architecture are configured with CMOS SRAM elements. Altera® devices are reconfigurable. Because every device is tested with a high-coverage production test program, you do not have to perform fault testing and can focus on simulation and design verification.

Stratix devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable configuration devices that configure Stratix devices via a serial data stream. Stratix devices can be configured in under 100 ms using 8-bit parallel data at 100 MHz. The Stratix device's optimized interface allows microprocessors to configure it serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat Stratix devices as memory and configure them by writing to a virtual memory location, making reconfiguration easy. After a Stratix device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

Operating Modes

The Stratix architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after

Figure 3–2. Stratix Device Remote Update



Note to Figure 3–2:

- (1) When the Stratix device is configured with the factory configuration, it can handle update data from EPC16, EPC8, or EPC4 configuration device pages and point to the next page in the configuration device.

Table 4–9. Overshoot Input Voltage with Respect to Duty Cycle (Part 2 of 2)

V _{in} (V)	Maximum Duty Cycle (%)
4.3	30
4.4	17
4.5	10

Figures 4–1 and 4–2 show receiver input and transmitter output waveforms, respectively, for all differential I/O standards (LVDS, 3.3-V PCML, LVPECL, and HyperTransport technology).

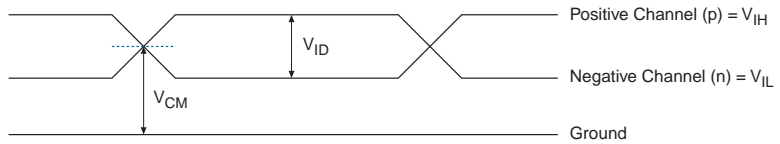
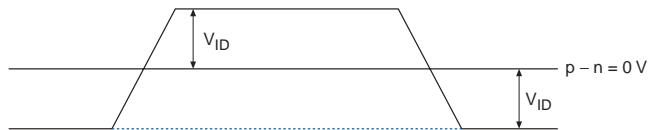
Figure 4–1. Receiver Input Waveforms for Differential I/O Standards**Single-Ended Waveform****Differential Waveform**

Table 4–77. EP1S30 External I/O Timing on Row Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.322		2.467		2.828		3.342		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.731	5.408	2.731	5.843	2.731	6.360	2.731	7.036	ns
t_{XZ}	2.758	5.462	2.758	5.899	2.758	6.428	2.758	7.118	ns
t_{ZX}	2.758	5.462	2.758	5.899	2.758	6.428	2.758	7.118	ns
t_{INSUPLL}	1.291		1.283		1.469		1.832		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.192	2.539	1.192	2.737	1.192	2.786	1.192	2.742	ns
t_{XZPLL}	1.219	2.539	1.219	2.793	1.219	2.854	1.219	2.824	ns
t_{ZXPLL}	1.219	2.539	1.219	2.793	1.219	2.854	1.219	2.824	ns

Table 4–78. EP1S30 External I/O Timing on Row Pins Using Global Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.995		2.089		2.398		2.830		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.917	5.735	2.917	6.221	2.917	6.790	2.917	7.548	ns
t_{XZ}	2.944	5.789	2.944	6.277	2.944	6.858	2.944	7.630	ns
t_{ZX}	2.944	5.789	2.944	6.277	2.944	6.858	2.944	7.630	ns
t_{INSUPLL}	1.337		1.312		1.508		1.902		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.164	2.493	1.164	2.708	1.164	2.747	1.164	2.672	ns
t_{XZPLL}	1.191	2.547	1.191	2.764	1.191	2.815	1.191	2.754	ns
t_{ZXPLL}	1.191	2.547	1.191	2.764	1.191	2.815	1.191	2.754	ns

Tables 4–85 through 4–90 show the external timing parameters on column and row pins for EP1S60 devices.

Table 4–85. EP1S60 External I/O Timing on Column Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	3.029		3.277		3.733		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.446	4.871	2.446	5.215	2.446	5.685	NA	NA	ns
t_{xZ}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns
t_{ZX}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns

Table 4–86. EP1S60 External I/O Timing on Column Pins Using Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.491		2.691		3.060		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.767	5.409	2.767	5.801	2.767	6.358	NA	NA	ns
t_{xZ}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{ZX}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{INSUPLL}	1.233		1.270		1.438		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.078	2.278	1.078	2.395	1.078	2.428	NA	NA	ns
t_{xZPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns
t_{ZXPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns

Table 4–87. EP1S60 External I/O Timing on Column Pins Using Global Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.000		2.152		2.441		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	3.051	5.900	3.051	6.340	3.051	6.977	NA	NA	ns
t_{XZ}	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
t_{ZX}	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
t_{INSUPLL}	1.315		1.362		1.543		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.029	2.196	1.029	2.303	1.029	2.323	NA	NA	ns
t_{XZPLL}	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns
t_{ZXPLL}	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns

Table 4–88. EP1S60 External I/O Timing on Row Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	3.144		3.393		3.867		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.643	5.275	2.643	5.654	2.643	6.140	NA	NA	ns
t_{XZ}	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns
t_{ZX}	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns

Table 4–120. Stratix Maximum Output Clock Rate for PLL[5, 6, 11, 12] Pins in Flip-Chip Packages (Part 2 of 2)

I/O Standard	-5 Speed Grade	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
SSTL-2 Class II (3)	200	200	167	167	MHz
SSTL-2 Class II (4)	200	200	167	167	MHz
SSTL-2 Class II (5)	150	134	134	134	MHz
SSTL-18 Class I	150	133	133	133	MHz
SSTL-18 Class II	150	133	133	133	MHz
1.5-V HSTL Class I	250	225	200	200	MHz
1.5-V HSTL Class II	225	200	200	200	MHz
1.8-V HSTL Class I	250	225	200	200	MHz
1.8-V HSTL Class II	225	200	200	200	MHz
3.3-V PCI	350	300	250	250	MHz
3.3-V PCI-X 1.0	350	300	250	250	MHz
Compact PCI	350	300	250	250	MHz
AGP 1×	350	300	250	250	MHz
AGP 2×	350	300	250	250	MHz
CTT	200	200	200	200	MHz
Differential 1.5-V HSTL C1	225	200	200	200	MHz
Differential 1.8-V HSTL Class I	250	225	200	200	MHz
Differential 1.8-V HSTL Class II	225	200	200	200	MHz
Differential SSTL-2 (6)	200	200	167	167	MHz
LVPECL (2)	500	500	500	500	MHz
PCML (2)	350	350	350	350	MHz
LVDS (2)	500	500	500	500	MHz
HyperTransport technology (2)	350	350	350	350	MHz

Table 4–125. High-Speed I/O Specifications for Flip-Chip Packages (Part 4 of 4) Notes (1), (2)														
Symbol	Conditions	-5 Speed Grade			-6 Speed Grade			-7 Speed Grade			-8 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{DUTY}	LVDS ($J = 2$ through 10)	47.5	50	52.5	47.5	50	52.5	47.5	50	52.5	47.5	50	52.5	%
	LVDS ($J = 1$) and LVPECL, PCML, HyperTransport technology	45	50	55	45	50	55	45	50	55	45	50	55	%
t_{LOCK}	All			100			100			100			100	μs

Notes to Table 4–125:

- (1) When $J = 4, 7, 8$, and 10, the SERDES block is used.
 (2) When $J = 2$ or $J = 1$, the SERDES is bypassed.

